IN THE ABSTRACT

Please replace the paragraph beginning at page 20, line 6, with the following re-written paragraph:

Abstract of the Disclosure

~~A method of fabricating a zero signal degradation solder bridge electrical connection for connecting adjacent conducting pads of a printed circuit board, and a printed circuit board having at least one of these solder bridge electrical connections. In the method, a stencil, having an opening that corresponds to the adjacent conducting pads and at least a portion of the surface area of the printed circuit board between the adjacent conducting pads, is placed on the surface of printed circuit board. Solder paste is then applied to the stencil such that the solder paste flows through the stencil opening and onto the adjacent conducting pads and at least a portion of the surface area of the printed circuit board between the pads. The stencil is then removed and the printed circuit board is subjected to reflow soldering, thereby fabricating a printed circuit board having a solder bridge electrical connector between adjacent conducting pads.~~ A method of fabricating a substantially zero signal degradation electrical connection on a printed circuit board includes providing a printed circuit board defined by a dielectric structure core. The dielectric structure core has a first surface, which includes a first connecting pad having an edge and a second connecting pad having an edge separated from an adjacent to the edge of the first conducting pad. The edges of the first and second conducting pads define therebetween a surface area of the first surface. A solder paste is applied on the first and second conducting pads and on the first surface of the dielectric structure core. The solder paste at least partially covers the surface area of the first surface between the edges of the first and second conducting pads, thereby forming a substantially zero signal degradation electrical connection between the first and second conducting pads.